



# ***AOS Semiconductor Product Reliability Report***

**AOTF4185**, rev B

**Plastic Encapsulated Device**

**ALPHA & OMEGA Semiconductor, Inc**

**[www.aosmd.com](http://www.aosmd.com)**



This AOS product reliability report summarizes the qualification result for AOTF4185. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOTF4185 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be monitored on a quarterly basis for continuously improving the product quality.

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### I. Product Description:

The AOTF4185 combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

-RoHS Compliant

Details refer to the datasheet.

### II. Die / Package Information:

	<b>AOTF4185</b>
<b>Process</b>	Standard sub-micron Low voltage P channel process
<b>Package Type</b>	3 leads TO220FL
<b>Lead Frame</b>	Bare Cu
<b>Die Attach</b>	Soft solder
<b>Bond wire</b>	Al & Au wire
<b>Mold Material</b>	Epoxy resin with silica filler
<b>Moisture Level</b>	Up to Level 1 *
<b>Note</b> * based on info provided by assembler and mold compound supplier	

### III. Result of Reliability Stress for AOTF4185

Test Item	Test Condition	Time Point	Lot Attribution	Total Sample size	Number of Failures	Reference Standard
MSL Precondition	168hr 85°c /85%RH +3 cycle reflow @250°c	-	11 lots	1815pcs	0	JESD22-A113
HTGB	Temp = 150°c , Vgs=100% of Vgsmax	168hrs 500 hrs 1000 hrs	1 lot  (Note A*)	77pcs  77 pcs / lot	0	JESD22-A108
HTRB	Temp = 150°c , Vds=80% of Vdsmax	168hrs 500 hrs 1000 hrs	1 lot  (Note A*)	77pcs  77 pcs / lot	0	JESD22-A108
HAST	130 +/- 2°c , 85%RH, 33.3 psi, Vgs = 80% of Vgs max	100 hrs	5 lots  (Note A*)	275pcs  55 pcs / lot	0	JESD22-A110
Pressure Pot	121°c , 29.7psi, RH=100%	96 hrs	11 lots  (Note A*)	847pcs  77 pcs / lot	0	JESD22-A102
Temperature Cycle	-65°c to 150°c , air to air,	250 / 500 cycles	9 lots  (Note A*)	693pcs  77 pcs / lot	0	JESD22-A104

**Note A:** The reliability data presents total of available generic data up to the published date.

### IV. Reliability Evaluation

**FIT rate (per billion): 46**

**MTTF = 2478 years**

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the selected product (AOTF4185). Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

$$\text{Failure Rate} = \text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)] = 1.83 \times 10^9 / [2 \times 2 \times 77 \times 500 \times 258] = 46$$

$$\text{MTTF} = 10^9 / \text{FIT} = 2.17 \times 10^7 \text{hrs} = 2478 \text{ years}$$

**Chi<sup>2</sup>** = Chi Squared Distribution, determined by the number of failures and confidence interval

**N** = Total Number of units from HTRB and HTGB tests

**H** = Duration of HTRB/HTGB testing

**Af** = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

$$\text{Acceleration Factor [Af]} = \text{Exp} [Ea / k (1/Tj u - 1/Tj s)]$$

**Acceleration Factor ratio list:**

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
Af	258	87	32	13	5.64	2.59	1

**Tj s** = Stressed junction temperature in degree (Kelvin), K = C+273.16

**Tj u** = The use junction temperature in degree (Kelvin), K = C+273.16

**k** = Boltzmann's constant, 8.617164 X 10<sup>-5</sup>eV / K